



PARA LIGHT ELECTRONICS CO., LTD.

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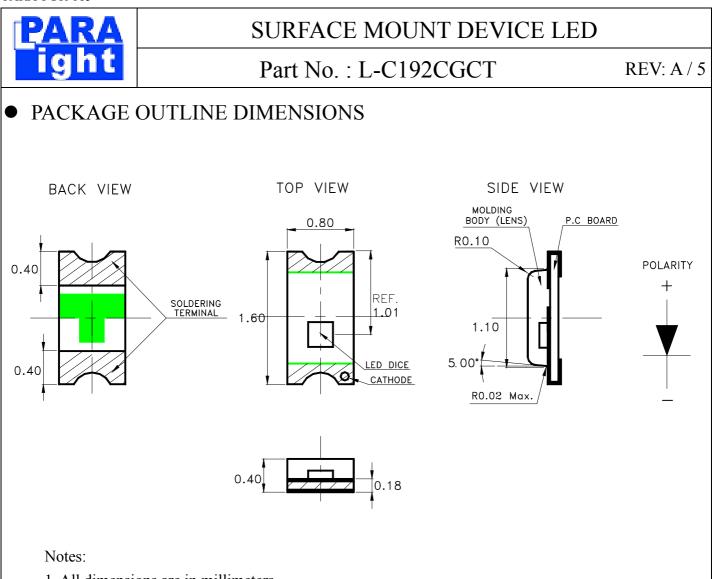
DATA SHEET

PART NO.: L-C192CGCT

REV: <u>A / 5</u>

CUSTOMER'S APPROVAL :	I	DCC :	
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- 1. All dimensions are in millimeters.
- 2. Tolerance is \pm 0.1mm (.004") unless otherwise noted.

Features

- * Extra thin 0.4mm, Top view, Wide view angle, single color SMD chip LED.
- * Special for Cellular Phone keypad / LCD backlighting or thin touch button LED backlighting.
- * Packing in 8mm tape on 7" diameter reels.
- * Compatible with automatic Pick & Place equipment.
- * Compatible with Reflow soldering and Wave soldering processes.
- * EIA STD package.(ANSI/EIA-481-B-2001)
- * I.C. compatible, low current application
- * Pb free product.
- * Meet RoHS Green Product.

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PARA-FOR-068

SURFACE MOUNT DEVICE LED Part No. : L-C192CGCT REV: A / 5

• CHIP MATERIALS

- * Dice Material : AlInGaP
- * Light Color : Super Green
- * Lens Color : Water Clear

• Absolute Maximum Ratings(Ta=25°C)

Symbol	Parameter	Rating	Unit
PD	Power Dissipation	60	mW
IPF	Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	60	mA
IF	Continuous Forward Current	25	mA
-	De-rating Linear From 25°C	0.25	mA/°C
VR	Reverse Voltage	5	V
ESD	Electrostatic Discharge Threshold(HBM)Note A	2000	V
Topr	Operating Temperature Range	$-40 \sim +85$	°C
Tstg	Storage Temperature Range	$-40 \sim +85$	°C

Note A :

HBM : Human Body Model. Seller gives no other assurances regarding the ability of to withstand ESD.

• Electro-Optical Characteristics(Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition
Luminous Intensity	IV	18	30		mcd	IF=20mA
Viewing Angle	2 0 1/2		130		deg	Note 2
Peak Emission Wavelength	λp		571		nm	Measurement @Peak
Dominant Wavelength	λd		570		nm	IF=20mA
Spectral Line Half-Width	Δλ		15		nm	
Forward Voltage	VF		2.0	2.3	V	IF =20mA
Reverse Current	IR			10	μA	VR = 5V

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SURFACE MOUNT DEVICE LED

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• Bin Code List

Luminous Intensity(IV), Unit:mcd@20mA			
Bin Code	Min	Max	
М	18.0	28.0	
Ν	28.0	45.0	
Р	45.0	71.0	

Forward Voltage(VF), Unit:V@20mA			
Bin Code	Min	Max	
4	1.90	2.00	
5	2.00	2.10	
6	2.10	2.20	
7	2.20	2.30	

Tolerance of each bin are $\pm 15\%$

Tolerance of each bin are ± 0.1 Volt

Dominant Wavelength (Hue), Unit: nm@20mA		
Bin Code	Min	Max
GA	567.0	570.0
GB	570.0	573.0
GC	573.0	576.0

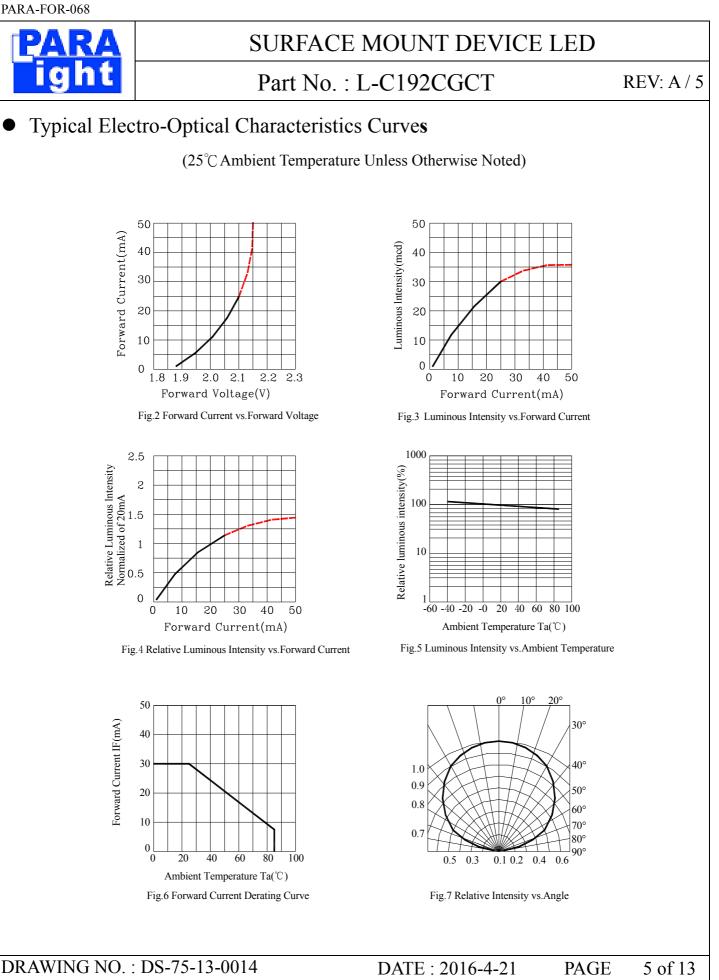
Tolerance of each bin are ± 1 nm

Notes:

- 1. Luminous intensity is measured with a light sensor and filter combination that proximities the CIE eye-response curve.
- 2. θ 1/2 is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- 3. Caution in ESD :

Static Electricity and surge damages the LED. It is recommended use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

4. Major standard testing equipment by "Instrument System" Model : CAS140B Compact Array Spectrometer and "KEITHLEY" Source Meter Model : 2400.



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• Label Explanation



ITEM CODE:PARRA LIGHT

PART NO: L-C192CGCT IV --- Luminous Intensity Code LOT NO: ΕM S L

В А C D A---EM: Emos Code B---S:SMD L---Local D----Year

E---Month

F---SPEC.

PACKING QUANTITY OF BAG :

3000pcs for 150, 170, 110, 155, 115 series

09

Е

12

0110

F

4000pcs for 191 series

5000pcs for 192 series

DATE CODE: <u>2012</u> <u>09</u> 10 Ι G Η

G--- Year H--- Month I --- Day

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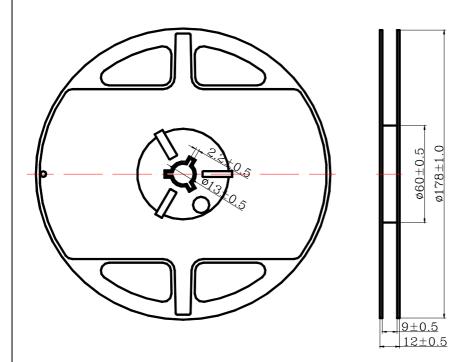
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• Reel Dimensions

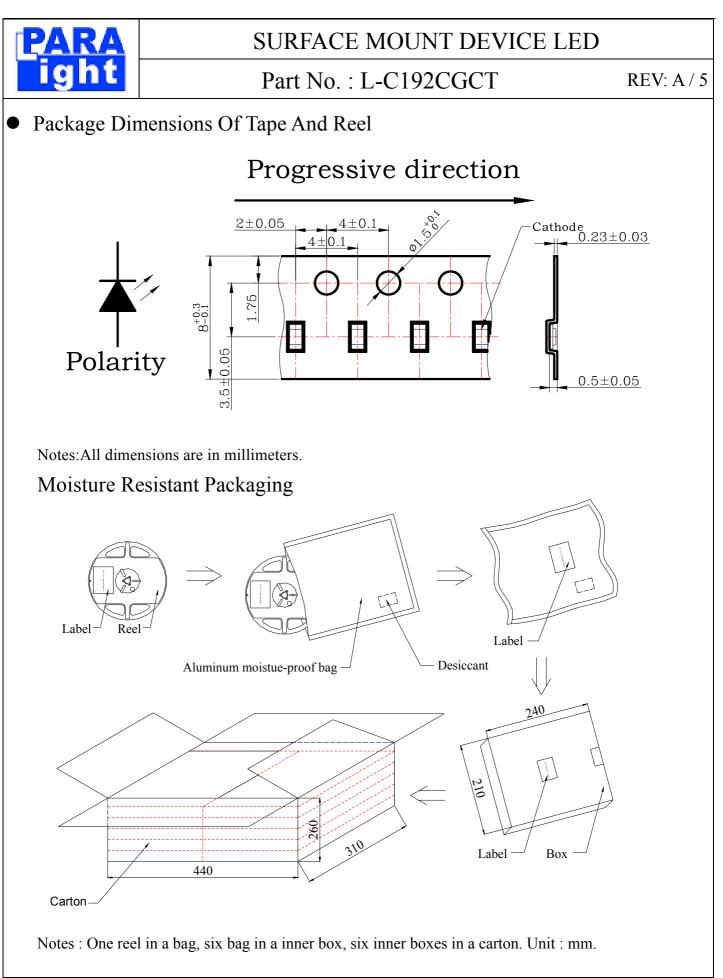


Notes:

- 1. Taping Quantity : 5000pcs max
- 2. The tolerances unless mentioned is $\pm\,0.1\text{mm},\text{Angle}\,\pm\,0.5\,^\circ\,$, Unit : mm

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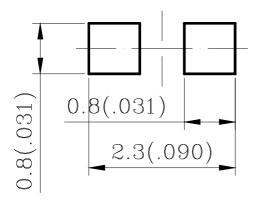
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• Cleaning

- * If cleaning is required , use the following solutions for less than 1 minute and less than 40° C.
- * Appropriate chemicals: Ethyl alcohol and isopropyl alcohol.
- Effect of ultrasonic cleaning on the LED resin body differs depending on such factors as the oscillator output, size of PCB and LED mounting method. The use of ultrasonic cleaning should be enforced at proper output after confirming there is no problem.

Suggest Soldering Pad Dimensions



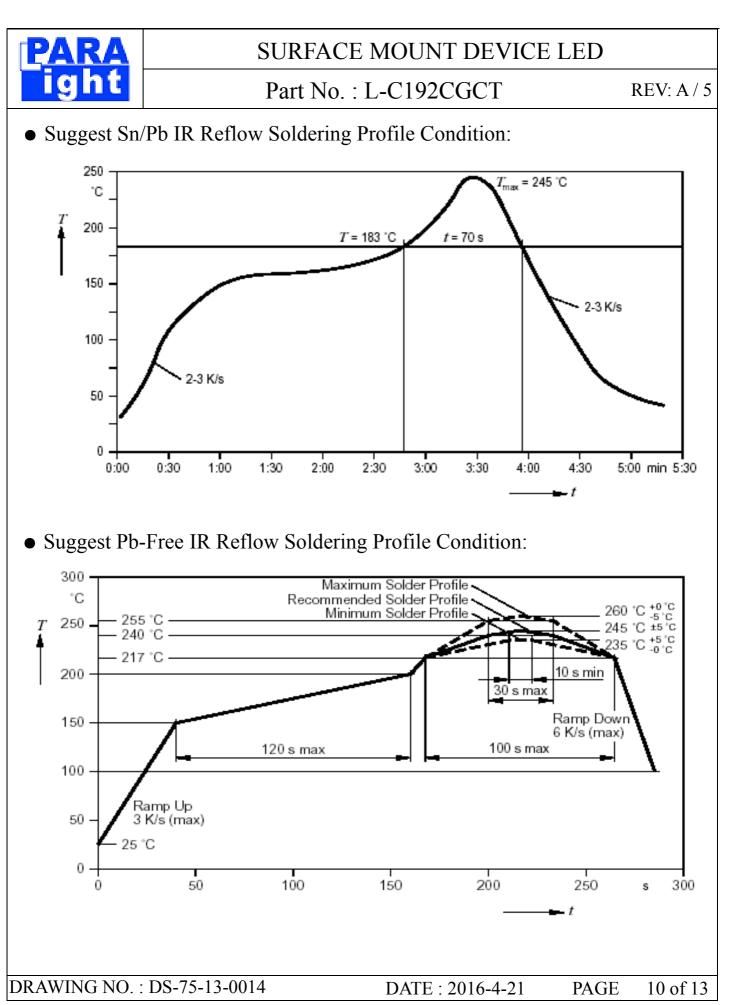
Direction of PWB camber

and go to reflow furnace

Notes : Suggest stencil print screen thickness are 0.10mm maximum.

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• CAUTIONS

1. Application Limitation :

The LED's described here are intended to be used for ordinary electronic equipment(such as office equipment, communication equipment and household application).Consult PARA's sales in advance for information on application in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LED's may directly jeopardize life or health (such as airplanes, automobiles, traffic control equipment, life support system and safety devices).

2.Storage :

Before opening the package :

The LEDs should be kept at 5°C to 30°C or less and 85%RH or less. The LEDs should be used within a year.

After opening the package :

The LEDs should be kept at 5°C to 30°C or less and 70%RH or less. The LEDs should be soldered within 168 hours(7 days) after opening the package.

Please avoid rapid transitions in ambient temperature in high humidity environments where condensation may occur.

LEDs stored out of their original packaging for more than one week should be baked at about 60°C for at least 20 hours before solder assembly.

3.Soldering

Do not apply any stress to the lead frame during soldering while the LED is at high temperature. Recommended soldering condition.

Reflow Soldering :

Pre-heat 120~150°C, 120sec. MAX., Peak temperature : 240°C Max. Soldering time : 10 sec Max. Soldering Iron : (Not recommended)

Temperature 300°C Max., Soldering time : 3 sec. Max.(one time only), power dissipation of iron : 20W Max. use SN60 solder of solder with silver content and don't to touch LED lens when soldering. Wave soldering :

Pre-heat 100°C Max, Pre-heat time 60 sec. Max, Solder wave 260°C Max, Soldering time 5 sec. Max. performed consecutively cooling process is required between 1st and 2nd soldering processes.



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4. Lead-Free Soldering

For Reflow Soldering :

- 1 Pre-Heat Temp: 150-180°C,120sec.Max.
- 2 Soldering Temp: Temperature Of Soldering Pot Over 230°C,40sec.Max.
- 3 $\$ Peak Temperature: 260 $^\circ\!\mathrm{C}\,$, 5sec.
- 4 Reflow Repetition: 2 Times Max.
- 5 × Suggest Solder Paste Formula : 93.3 Sn/3.1 Ag/3.1 Bi/0.5 Cu

For Soldering Iron (Not Recommended) :

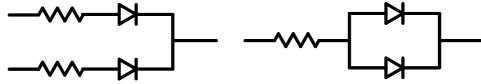
- 1 · Iron Tip Temp: 350°C Max.
- 2 Soldering Iron: 30w Max.
- 3 Soldering Time: 3 Sec. Max. One Time.

For Dip Soldering :

- 1 > Pre-Heat Temp: 150°C Max. 120 Sec. Max.
- $2 \cdot Bath Temp: 265^{\circ}C Max.$
- 3 Dip Time: 5 Sec. Max.
- 5. Drive Method

Circuit model A

Circuit model B



(A)Recommended circuit.

(B)The difference of brightness between LED's could be found due to the Vf-If characteristics of LED.



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6.Reliability Test

Classification	Test Item	Test Condition	Reference Standard
Endurance Test	Operation Life	Ta= Under Room Temperature As Per Data Sheet Maximum Rating *Test Time= 1000HRS (-24HRS,+72HRS)*@20mA.	MIL-STD-750D:1026 (1995) MIL-STD-883D:1005 (1991) JIS C 7021:B-1 (1982)
	High Temperature High Humidity Storage	IR-Reflow In-Board, 2 Times Ta= 65±5°C,RH= 90~95% *Test Time= 1000HRS±2HRS	MIL-STD-202F:103B(1980) JIS C 7021:B-11(1982)
	High Temperature Storage	Ta= 105±5℃ Test Time= 1000HRS (-24HRS,72HRS)	MIL-STD-883D:1008 (1991) JIS C 7021:B-10 (1982)
	Low Temperature Storage	Ta= -55±5°C *Test Time=1000HRS (-24HRS,72H RS)	JIS C 7021:B-12 (1982)
Environmental Test	Temperature Cycling	105±5℃ -55±5℃ 10mins 10mins 10mins 100 Cycles	MIL-STD-202F:107D (1980) MIL-STD-750D:1051(1995) MIL-STD-883D:1010 (1991) JIS C 7021:A-4(1982)
	Thermal Shock	IR-Reflow In-Board, 2 Times105±5℃-55℃±5℃10mins10mins100 Cycles	MIL-STD-202F:107D(1980) MIL-STD-750D:1051(1995) MIL-STD-883D:1011 (1991)
	Solder Resistance	Tsol= $260 \pm 5^{\circ}$ C Dwell Time= 10 ± 1 sec	MIL-STD-202F:210A(1980) MIL-STD-750D:2031(1995) JIS C 7021:A-1(1982)
	Solder ability	Tsol= $235 \pm 5^{\circ}$ C Immersion time 2 ± 0.5 sec Immersion rate 25 ± 2.5 mm/sec Coverage $\geq 95\%$ of the dipped surface	MIL-STD-202F:208D(1980) MIL-STD-750D:2026(1995) MIL-STD-883D:2003(1991) IEC 68 Part 2-20 JIS C 7021:A-2(1982)

7.Others:

The appearance and specifications of the product may be modified for improvement without notice.

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